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IN THE CLAIMSAmendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:  
an insulating substrate having an obverse surface, a reverse surface opposite to the obverse surface, and a plurality of side surfaces extending between the obverse surface and the reverse surface, the substrate being elongate in one direction;  
formed with a die pad made of a metal film and formed on the obverse surface of the substrate;  
a pair of electrode terminals made of a metal film and extending from the obverse surface of the substrate onto the reverse surface via selected ones of the side surfaces;  
a semiconductor chip bonded to an obverse surface of the die pad with a die bonding material; and  
a molded portion made of a synthetic resin covering the obverse surface of the substrate without covering the side surfaces and the reverse surface for packaging the semiconductor chip;  
wherein a narrow patterned conductor made of a metal film is provided between the die pad and one of the electrode terminals to integrally connect the die pad and the electrode terminal to each other, the die pad having a length and a width which are 0.50 to 1.50 times a length and a width of the semiconductor chip, respectively; and  
wherein the semiconductor chip comprises an LED chip, the molded portion being light-permeable; and  
wherein the die pad, the pair of electrode terminals and the narrow patterned conductor in combination provide an overall conductor pattern that is asymmetrical with respect to a longitudinal centerline of the insulating substrate extending in said one direction, the narrow patterned conductor extending obliquely and being offset from the longitudinal centerline of the insulating substrate.

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2. (Original) The semiconductor device according to claim 1, wherein the die pad has a side surface integrally formed with a narrow extension projecting outward from the die pad.
3. (Original) The semiconductor device according to claim 1, wherein the die pad is formed with a recess of a size insufficient to receive the semiconductor chip.
4. (Original) The semiconductor device according to claim 1, wherein the die pad has a side surface integrally formed with a narrow extension projecting outward from the die pad, and wherein the die pad is formed with a recess of a size insufficient to receive the semiconductor chip.

5-12. (Canceled)